

MPSW3725



NPN Transistor

This device is designed for high current, low impedance line driver applications. Sourced from Process 26.

Absolute Maximum Ratings TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V _{CEO}	Collector-Emitter Voltage	40	V	
V _{CBO}	Collector-Base Voltage	60	V	
V _{EBO}	Emitter-Base Voltage	6.0	V	
I _C	Collector Current - Continuous	1.2	Α	
T _J , T _{stg}	Operating and Storage Junction Temperature Range	-55 to +150	°C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics TA = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
		MPSW3725	
P _D	Total Device Dissipation	1.0	W
	Derate above 25°C	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	°C/W

(continued)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
OFF CHAF	RACTERISTICS					
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage*	$I_C = 10 \text{ mA}, I_B = 0$	40			V
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	$I_C = 10 \mu A, V_{BE} = 0$	60			V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_{CE} = 0$	60			V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 10 \mu A, I_C = 0$	6.0			V
I _{CBO}	Collector Cutoff Current	$V_{CB} = 50 \text{ V}, I_E = 0$ $V_{CB} = 50 \text{ V}, I_E = 0, T_A = 100^{\circ}\text{C}$			100 10	nA μA
		$ \begin{array}{l} I_{C} = 100 \text{mA}, V_{CE} = 1.0 \text{V}, T_{A} = -55 ^{\circ} \text{C} \\ I_{C} = 300 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_{C} = 500 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \end{array} $	30 40 35			
h _{FE}	DC Current Gain				180	
		$ \begin{array}{l} I_C = 500 \text{ mA}, V_{CE} = 1.0 \text{ V} \\ I_{C} = 500 \text{mA}, V_{CE} = 1.0 \text{V}, T_{A} = -55^{\circ}\text{C} \\ I_C = 800 \text{ mA}, V_{CE} = 2.0 \text{ V} \\ I_C = 1.0 \text{ A}, V_{CE} = 5.0 \text{ V} \\ \end{array} $	35 20 20 25			
V _{CE(sat)}	Collector-Emitter Saturation Voltage	$I_{C} = 100 \text{ mA}, I_{B} = 1.0 \text{ mA}$ $I_{C} = 100 \text{ mA}, I_{B} = 10 \text{ mA}$ $I_{C} = 100 \text{ mA}, I_{B} = 30 \text{ mA}$ $I_{C} = 300 \text{ mA}, I_{B} = 50 \text{ mA}$ $I_{C} = 800 \text{ mA}, I_{B} = 80 \text{ mA}$ $I_{C} = 1.0 \text{ A}, I_{B} = 100 \text{ mA}$			0.25 0.26 0.4 0.52 0.8 0.95	V V V V
V _{BE(sat)}	Base-Emitter Saturation Voltage	$I_C = 1.0 \text{ M}, I_B = 1.0 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 1.0 \text{ mA}$ $I_C = 100 \text{ mA}, I_B = 30 \text{ mA}$ $I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$ $I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$ $I_C = 800 \text{ mA}, I_B = 80 \text{ mA}$ $I_C = 1.0 \text{ A}, I_B = 100 \text{ mA}$			0.76 0.86 1.1 1.2 1.5 1.7	V V V V V
SMALL SI	GNAL CHARACTERISTICS					
f _T	Current Gain - Bandwidth Product	I _C = 50 mA, V _{CE} = 10 V, f = 100 MHz	250			MHz

f _T	Current Gain - Bandwidth Product	$I_C = 50 \text{ mA}, V_{CE} = 10 \text{ V},$ f = 100 MHz	250		MHz
C _{obo}	Output Capacitance	$V_{CB} = 10 \text{ V}, I_{E} = 0,$ f = 1.0 MHz		25	pF
C _{ibo}	Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0,$ f = 1.0 MHz		100	pF

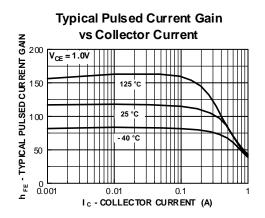
SWITCHING CHARACTERISTICS

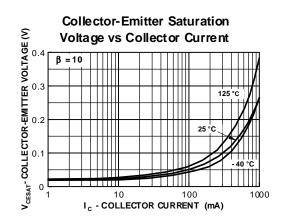
t _{on}	Turn-on Time	$V_{CC} = 30 \text{ V}, V_{BE} = 3.8 \text{ V},$	22	ns
t _d	Delay Time	$I_C = 500 \text{ mA}, I_{B1} = 50 \text{ mA}$	10	ns
tr	Rise Time	1	12	ns
t _{off}	Turn-off Time	V _{CC} = 30 V, I _C = 500mA	250	ns
ts	Storage Time	$I_{B1} = I_{B2} = 50 \text{ mA}$	235	ns
t _f	Fall Time	1	15	ns

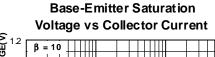
^{*}Pulse Test: Pulse Width $\leq\!300~\mu\text{s},$ Duty Cycle $\leq\!1.0\%$

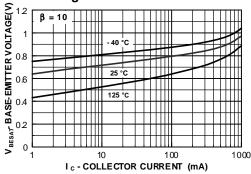
(continued)

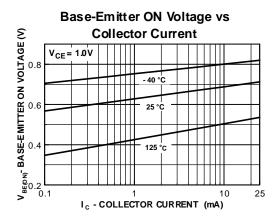
Typical Characteristics



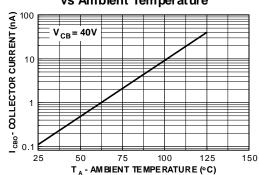




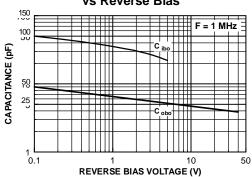




Collector-Cut off Current vs Ambient Temperature

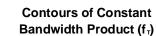


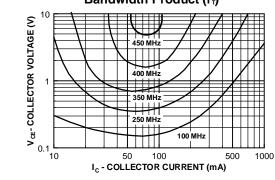
Input / Output Capacitance vs Reverse Bias



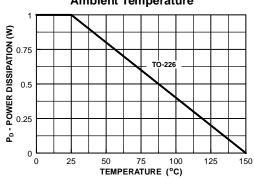
(continued)

Typical Characteristics (continued)



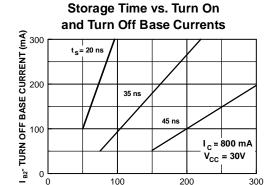


Power Dissipation vs Ambient Temperature

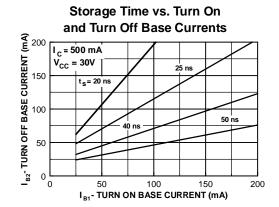


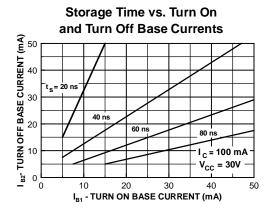
(continued)

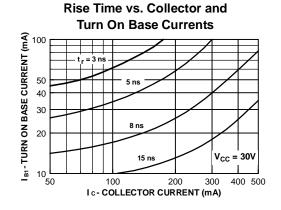
Typical Characteristics (continued)



I_{B1} - TURN ON BASE CURRENT (mA)

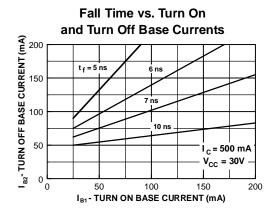


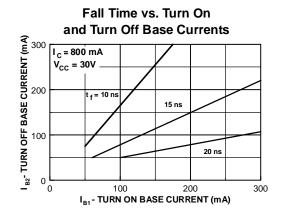


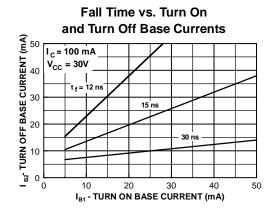


(continued)

Typical Characteristics (continued)







(continued)

Test Circuit

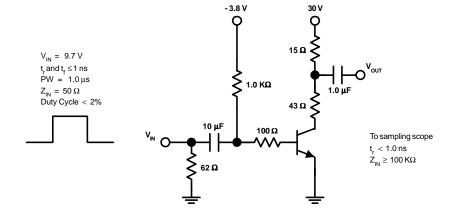


FIGURE 1: Switching Time Test Circuit (I $_{\rm c}$ = 500 mA, I $_{\rm B1}$ = 50 mA, I $_{\rm B2}$ = 50 mA)

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

 $ACEx^{TM}$ FASTr™ PowerTrench® SyncFET™ Bottomless™ QFET™ TinyLogic™ GlobalOptoisolator™ QSTM UHC™ CoolFET™ GTO™ **VCX**TM $CROSSVOLT^{TM}$ QT Optoelectronics™ HiSeC™

DOME™ ISOPLANAR™ Quiet Series™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition		
Advance Information Formative or In Design		This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.		
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.		
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.		